

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Akihiko ENDO et al.

**Office of Initial Patent
Examination
Customer Service Center**

Appln. No. : 10/569,942

Filed : February 28, 2006

For : METHOD FOR MANUFACTURING BONDED WAFER

REQUEST FOR OFFICIAL FILING RECEIPT

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop _____
Randolph Building
401 Dulany Street
Alexandria, VA 22314

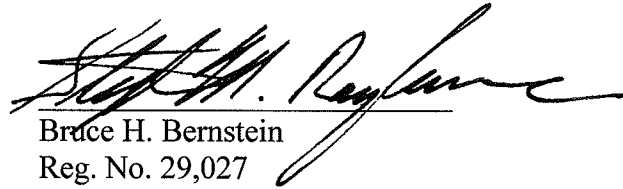
Sir:

Applicants respectfully request that the United States Patent and Trademark Office issue an Official Filing Receipt in the above-identified application.

The above-identified application was filed in the U.S. Patent and Trademark Office on February 28, 2006. For the convenience of the Patent and Trademark Office, Applicants enclose herewith copies of our date-stamped mailroom filing receipt evidencing the filing of the application and the Executed Declaration in the U.S. Patent and Trademark Office on February 28, 2006.

Should there be any questions concerning this application, the undersigned may be contacted at the telephone number listed below.

Respectfully submitted,
Akihiko ENDO et al.



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2/28/2006

File In: Mailroom

The Patent Office Date stamp hereon is an acknowledgement that, on the date indicated, the Patent Office received the following:

W/ National phase of PCT/JP2004/012633, filed Sep. 1, 2004
W/ International Application as published in Japanese (1 page of cover sheet)

- (X) Amendment Preliminary
(Y) Executed Assignment and cover letter
() Executed S.E.S. () S.E.S. Assertion
() Req. for Ext. of Time
(X) Fee Filing (X)
Recording (X)
Issue ()
Extension ()
Publication ()

- () Fee Transmittal
() Maintenance Fee Payment
() PTOL-85B Issue Fee & Publication Fee (with Copy)
() Cover Letter Regarding Drawings
() Design Patent Application Transmittal
() Utility Patent Application Transmittal
() Provisional Application Cover Sheet
() Request for Continued Examination (RCE) including Submission
() Cover Letter
() Credit Card Payment for \$ (Form PTO-2038)
(X) Check No. 57278 for \$ 940.00
() Rule 53b and 53f Letter for Unexecuted Application
() Application Data Sheet

- (X) Claim of Priority & Certified Copy of _____

- (X) Declaration (Y) Executed
() Unexecuted
() Copy from parent
(Y) Transmittal Letter
(X) Patent Application (English translation)

- () Provisional () Reexam
() Reissue () Design
() Continuation () CIP
() Divisional

20 pages (w/abstract)

6 claims 1 independent

3 sheets of drawings

86 figures

- () I.D.S. form PTO-1449 & Documents () as attached
() as listed on reverse
(X) One self-addressed postcard
() Certification under 1.97(e)
() Certificate of Mailing (C-O-M)
() Returned Envelope

W/ International Application as filed in Japanese (12 pages of specifications + 3 sheets of drawings)
In the matter of : METHOD FOR MANUFACTURING BONDED WAFER

Applicant : Akihiko ENDO et al.

Application No. : Nit Yut Anigud

Patent No. :

Filed : currently Herewith

Issued :

Docket : P29123

(X) PCT/ISA/210
(Y) PCT/IB/306
(Y) PCT/IB/308
(Y) PCT/RO/101 (in JP)

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